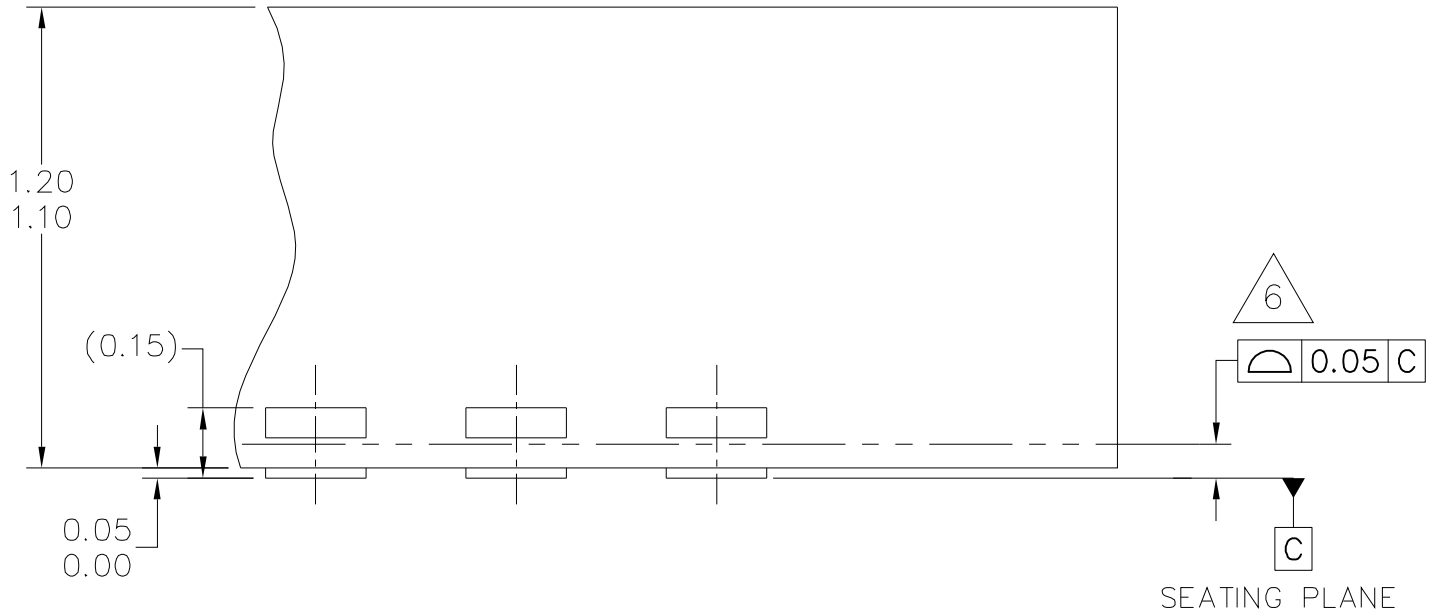


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TITLE: QFN-COL, 3 X 3 X 1.2, 0.5 PITCH, 16 TERMINAL		DOCUMENT NO: 98ASA00318D      REV: B	
		STANDARD: NON JEDEC	
		SOT1680-1	07 JAN 2016






DETAIL G

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	STANDARD: NON JEDEC		
	SOT1680-1		07 JAN 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. THIS IS NON JEDEC REGISTERED PACKAGE.
4.  PIN #1 ID ON TOP WILL BE LASER MARKED.
5.  THIS DIMENSION APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL TIP. IF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL, THIS DIMENSION SHOULD NOT BE MEASURED IN THAT RADIUS AREA.
6.  COPLANARITY APPLIES TO LEADS AND ALL OTHER BOTTOM SURFACE METALLIZATION.
7. MIN. METAL GAP SHOULD BE 0.2MM.

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